



Toshiba releases medium voltage, high current photorelay in small package

Latest trench MOSFET process delivers replacement for mechanical relays

Düsseldorf, Germany, 20 February 2018 – Toshiba Electronics Europe has announced the launch of a new photorelay in a small 2.54SOP4 package that is just 2.1mm high with a 2.54mm pitch.

Fabricated using the latest U-MOS VIII trench MOSFET process, the new TLP3145 combines an off-state output terminal voltage of 200V with a controllable on-state current of up to 0.4A continuously or 1.2A when pulsed. This makes TLP3145 a suitable replacement for a 1A mechanical relay that is used to control a 100V AC circuit.

Replacing a mechanical relay with a photorelay that is smaller and does not need a relay driver increases system reliability and supports space-saving design. The TLP3145 is conveniently rated for an operating temperature range of -40°C to +110°C, making it easier to allow for a temperature margin in system-level thermal design.

The TLP3145 turns on or off in just 0.5ms (max.) and consumes a max. of 1µA in its OFF-state. The new device offers an isolation voltage of 1500Vrms and is approved to the UL1577 Safety Standard.

Notes:

The latest Gartner market report recognises Toshiba as the leading manufacturer of optocouplers by sales in 2015 and 2016, with 23% of sale-based market share in CY2016. (Source: Gartner, Inc. "Market Share: Semiconductor Devices and Applications Worldwide 2016" 30 March, 2017).

Toshiba Electronic Devices & Storage Corporation will continue to deliver products that meet the needs of customers by promoting the development of a diverse portfolio of photocouplers and photorelays tailored to market trends.

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About Toshiba Electronics Europe

[Toshiba Electronics Europe GmbH](#) (TEE) is the European electronic components business of [Toshiba Electronic Devices and Storage Corporation](#). TEE offers European consumers and businesses a wide variety of innovative hard disk drive (HDD) products plus semiconductor solutions for automotive, industrial, IoT, motion control, telecoms, networking, consumer and white goods applications. The company's broad portfolio encompasses integrated wireless ICs, power semiconductors, microcontrollers, optical semiconductors, ASICs, ASSPs and discrete devices ranging from diodes to logic ICs.

Formed in 1973 in Neuss, Germany, TEE has headquarters in Düsseldorf, Germany, with branch offices in Germany, France, Italy, Spain, Sweden and the United Kingdom providing design, manufacturing, marketing and sales. Company president is Mr. Akira Morinaga.

For more company information visit TEE's web site at www.toshiba.semicon-storage.com.

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